ABSTRACT OF THE DISCLOSURE

WAFER POLISHING APPARATUS

Sensors detect a stock removal of a wafer during polishing, and a CPU calculates the stock removal in accordance with information from the sensors. The CPU compares the actual stock removal detected by the sensors and a model stock removal stored in RAM, and determines timings for dressing and replacing said polishing pad in accordance with a difference between the actual stock removal and the model stock removal. The determination results are shown on a display.

This Sheet Has Been Replaced

